

Title (en)  
ELECTRONIC POWER MODULE

Title (de)  
ELEKTRONISCHES LEISTUNGSMODUL

Title (fr)  
MODULE ELECTRONIQUE DE PUISSANCE

Publication  
**EP 3360160 A1 20180815 (FR)**

Application  
**EP 16790655 A 20161004**

Priority  
• FR 1559466 A 20151005  
• FR 2016052536 W 20161004

Abstract (en)  
[origin: WO2017060602A1] The electronic power module (1) comprises power connection terminals (10, 11, 12, 15) intended to be connected to an input device (20) and to an output device (19), electronic chips (2, 7, 8, 9) and power tracks (4, 5, 6, 13, 14) electrically connected to the chips and to the terminals. According to the invention, the chips are mounted directly on the power tracks (4, 5, 6) formed at least partially from segments of hollow metal profile sections (4, 5, 6, 13, 14) that have, at least partially, a flat outer surface. According to another feature, a first set of tracks (4, 5, 6) is electrically insulated from a second set of tracks (13, 14) by at least a first substrate (16) formed from a laminate comprising a first electrically insulating material and a second electrically conductive material.

IPC 8 full level  
**H01L 23/473** (2006.01); **H01L 23/492** (2006.01); **H01L 23/495** (2006.01); **H01L 25/07** (2006.01); **H01L 25/16** (2006.01)

CPC (source: EP)  
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**H01L 23/49575** (2013.01); **H01L 2224/49111** (2013.01); **H01L 2224/49175** (2013.01); **H01L 2924/00014** (2013.01); **H01L 2924/13055** (2013.01);  
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C-Set (source: EP)  
**H01L 2924/00014** + **H01L 2224/45099**

Citation (search report)  
See references of WO 2017060602A1

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Designated extension state (EPC)  
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DOCDB simple family (publication)  
**FR 3042078 A1 20170407; FR 3042078 B1 20190322**; EP 3360160 A1 20180815; WO 2017060602 A1 20170413

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